Thursday, March 26th, 2020 at 12:00

Electronic Packaging: The Next 20 Years

Presented by: Intel, Beth Keser Ph.D., Director of Packaging Engineering

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Abstract
The future of electronic packaging is bright for package engineer as many new applications depend on advanced packaging solutions rather than Moore's Law for improved performance and cost. Current mechanical, thermal, material, and electrical issues will multiply as solutions are required for heterogeneous integration, high reliability, low power, low loss, good thermal and electrical performance, and optimized cost and footprint. Advances in Fan-Out Wafer and Panel Level Packaging are adding value to the mobile, automotive, and IoT industries, but new package architectures and designs are needed to address 5G, Autonomous Driving, Artificial Intelligence, and Virtual/Augmented Reality. There are many packaging challenges ahead and significant advancements will be required in package innovation over the next 20 years.

Biography
BETH KESER, Ph.D., IMAPS President-Elect, a recognized global leader in the semiconductor packaging industry with over 22 years of experience, received her B.S. degree in Materials Science and Engineering from Cornell University and her Ph.D. from the University of Illinois at Urbana-Champaign. Beth's excellence in developing revolutionary electronic packages for semiconductor devices has resulted in 29 patents and patents pending and over 40 publications in the semiconductor industry. Currently, Beth leads the Packaging & Systems Technology department in the Product Enablement Solutions Group at Intel.

Previously, Beth led Qualcomm's Fan-Out and Fan-In Wafer Level Packaging Technology Development and NPI Group for over 7 years. Before joining Qualcomm in 2009, Beth led the Wafer-Level Chip Scale packaging team at Motorola and was manager of the Redistributed Chip Packaging Technology (RCP).

Logistics:

Thursday, March 26th, 2020 at 12:00 – 1:00 PM. Lunch will be provided.
Location: EMD Performance Materials, @ 6555 Nancy Ridge Drive, Suite #200, San Diego, CA 92123
RSVP required. Space is limited to 30 registrants due to room size; please sign up quickly.
$20.00 for members.
$25.00 for non-members.
$10 for students with an ID.
Please advise if you are non-U.S. citizen when you register. **Register here** , questions please contact Bill Ishii ----- bill@imaps.org